

Metal Mode Sputtering

Metal Target Materials	DC nDDR	AC nDDR	Max Power
	((nm)*(m/min))/(kW/m)		kW/m
Aluminum	9	7.65	90
Chromium	9.9	8.42	75
Copper	16.2	13.77	90
Germanium	9	7.65	37.5
Molybdenum	7.2	6.12	75
Nickel	12.6	10.71	75
Niobium	5.4	4.59	75
Silicon	4.5	3.83	20
Stainless Steel	6.5	5.20	100
Tantalum	4.5	3.83	75
Tin	9.9	8.42	75
Titanium	4.05	3.44	75
Tungsten	4.5	3.83	75
Zirconium	4.5	3.83	75

Conductive Ceramic Sputtering

Ceramic Target Materials	DC nDDR ((nm)*(m/min))/(kW/m)	Max Power kW/m
AZO	8.2	27
ITO	10	15

Reactive Sputtering

Mid Frequency AC/Pulse DC Reactive Sputtering				
Target Material	Coating Material	Typical DDR nm*m/min	Optimized DDR nm*m/min	Max Power kW/m
Aluminum	Al ₂ O ₃	20	60	75
Niobium	Nb ₂ O ₅	25	60	50
Silicon	SiO ₂	10	45	20
Titanium	TiO ₂	20	40	75
Titanium	TiN	10	22	75
Zinc	ZnO	16	120	25

This data is a collection of averaged published rates and of in-house testing; individual results may vary

This data is subject to change without notice; be sure to check all maximum power densities with target vendors first to avoid damaging targets